

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	245	(machine or apparatus or tool or device).ti. and (align\$4 near (plate or tool or surface)) and ((sample or crimp\$3) near (table or surface or plate))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:36
L2	312	(machine or apparatus or tool or device).ab. and (align\$4 near (plate or tool or surface)) and ((sample or crimp\$3) near (table or surface or plate))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:39
L3	130	2 not 1	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:36
L4	6463	(machine or apparatus or tool or device).ab. and (align\$4 with (plate or tool or surface)) and ((sample or crimp\$3) with (table or surface or plate))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:39

L5	5778	(machine or apparatus or tool or device).ti. and (align\$4 with (plate or tool or surface)) and ((sample or crimp\$3) with (table or surface or plate))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:39
L6	7198	(machine or apparatus or tool or device or system).ti. and (align\$4 with (plate or tool or surface)) and ((sample or crimp\$3) with (table or surface or plate))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:40
L7	145	6 and ((solder or bump) and ball)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:40
L8	139	7. not 2	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:43
L9	242	6 and ball and (wafer or semiconductor)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:43

L10	168	9 not 7	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:43
L18	20306	(bump and ball and form\$3)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:52
L19	407	(bump and ball and form\$3). ti.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:53
L20	41	(hidaka near masao).in.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:53
S1	3685	((29/592.1) or (29/825) or (29/407.01) or (29/407.09) or (29/407.1) or (29/525.13) or (29/559)).CCLS.	US-PGPU B; USPAT; USOCR	OR	OFF	2005/06/12 22:36
S2	3907	((29/464) or (29/466) or (29/468) or (29/709) or (29/714) or (29/721) or (29/759) or (29/760)).CCLS.	US-PGPU B; USPAT; USOCR	OR	OFF	2005/06/13 09:39

S4	3583	S2 not S1	US-PGPU B; USPAT; USOCR	OR	ON	2005/06/12 19:52
S5	898	((29/281.1) or (29/281.4)). CCLS.	US-PGPU B; USPAT; USOCR	OR	OFF	2005/06/12 22:04
S6	528	((29/464) or (29/466) or (29/468) or (29/709) or (29/714) or (29/721) or (29/759) or (29/760) or (29/281.1) or (29/281.4)). CCLS.	EPO; JPO; DERWEN T; IBM_TDB	OR	OFF	2005/06/12 22:15
S7	90	((29/407.01) or (29/407.09) or (29/407.1) or (29/525.13) or (29/559)).CCLS.	EPO; JPO; DERWEN T; IBM_TDB	OR	OFF	2005/06/12 22:41
S8	1763	((29/592.1) or (29/825)). CCLS.	EPO; JPO; DERWEN T; IBM_TDB	OR	OFF	2005/06/12 22:41
S9	0	S8 and (bump near ball near crimp\$3)	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/12 22:42
S10	0	S8 and (bump same ball same crimp\$3)	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/12 22:42
S11	0	S8 and (bump and ball and crimp\$3 and (device or apparatus or machine))	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/12 22:56
S12	0	S8 and (ball and crimp\$3 and (device or apparatus or machine))	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/12 22:56

S13	0	S8 and (bump and ball and crimp\$3)	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/12 22:57
S14	1	S8 and (bump and ball)	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/12 23:03
S15	2836	((269/54.4) or (269/54.5) or (269/55) or (269/58) or (269/59) or (269/289R) or (269/909)).CCLS.	US-PGPU B; USPAT; USOCR	OR	OFF	2005/06/12 23:04
S16	2	(bump adj ball adj crimp\$3 adj (apparatus or machine or device or tool))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 09:43
S17	2	(bump near ball near crimp\$3 near (apparatus or machine or device or tool))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 09:43
S18	10	(bump with ball with crimp\$3 with (apparatus or machine or device or tool))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 09:45

S19	23	(bump same ball same crimp\$3 same (apparatus or machine or device or tool))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 09:47
S20	13	S19-not S18	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 09:46
S21	5147	(bump same ball same (apparatus or machine or device or tool))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 09:47
S22	2409	(bump with ball with (apparatus or machine or device or tool))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 09:48
S23	562	(bump with ball with (apparatus or machine or device or tool)).ab.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 09:48

S24	59	S23 and wafer.ab.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 09:55
S25	58	S24 not S19	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 09:48
S26	95	S23 and wafer	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 09:55
S27	37	S26 not S25	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 09:58
S28	2	S23 and (align\$4 near (plate or tool or surface)) and ((sample or crimp\$3) near (table or surface or plate))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 13:29

S29	2	S23 and (align\$4 with (plate or tool or surface)) and ((sample or crimp\$3) with (table or surface or plate))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 10:01
S30	2	S23 and (align\$4 same (plate or tool or surface)) and ((sample or crimp\$3) same (table or surface or plate))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 10:01
S31	2	S23 and (align\$4 and (plate or tool or surface)) and ((sample or crimp\$3) and (table or surface or plate))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 10:02
S32	138	S21 and (align\$4 and (plate or tool or surface)) and ((sample or crimp\$3) and (table or surface or plate))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 10:02
S33	137	S32 not S26	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 10:10

S35	4	(Yukihiko near Isa).in.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 10:11
S36	89	(UMC near Japan).as.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 10:19
S37	34	((crimp\$3 or bond\$3) near (device or mechanism or tool)) and (align\$4 near (plate or tool or surface)) and ((sample or crimp\$3) near (table or surface or plate))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 10:22
S38	1905	((228/41) or (228/246) or (228/180.22)).CCLS.	US-PGPU B; USPAT; USOCR	OR	OFF	2005/06/13 10:59
S39	237	((228/41) or (228/246) or (228/180.22)).CCLS.	EPO; JPO; DERWEN T; IBM_TDB	OR	OFF	2005/06/13 11:19
S40	1565	(29/840).CCLS.	US-PGPU B; USPAT; USOCR	OR	OFF	2005/06/13 11:43
S41	703	(29/840).CCLS.	EPO; JPO; DERWEN T; IBM_TDB	OR	OFF	2005/06/13 11:43

S42	0	S41 and (bump near ball)	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 11:44
S43	0	S41 and ((bond\$3 or bump with ball)	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 11:44
S44	4	S41 and ((bond\$3 or bump and ball)	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 11:45
S45	26	S41 and ball	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/06/13 11:45